







INA2128

ZHCSRV7B - DECEMBER 1995 - REVISED MAY 2023

INA2128 双路低功耗仪表放大器

1 特性

低失调电压:50µV(最大值) 低温漂: 0.5 µV/°C(最大值) 低输入偏置电流:5nA(最大值) • 输入电压噪声: 1kHz 时为 8nV/ √Hz

• 高带宽: 1.3MHz (G = 1V/V) • 高 CMR: 120dB(最小值) • 输入保护电压可达 ±40V

• 宽电源电压范围: ±2.25V 至 ±18V 低静态电流:700µA(每通道) • 温度范围: -40°C至+85°C

封装: 16 引脚 SOIC

2 应用

压力变送器

温度变送器

• 称重计

心电图 (ECG)

模拟输入模块

数据采集 (DAQ)

3 说明

INA2128 是一款双路低功耗通用仪表放大器 (IA),可 提供出色的准确性。此器件采用多功能三级运算放大器 设计,尺寸小巧,适用于多种应用。即使在高增益(G = 100 时为 200 kHz)情况下,电流反馈输入电路也可 提供宽带宽。可通过单个外部电阻器在 1 到 10,000 范 围内设置任意增益。内部输入保护可经受高达 ±40V 的 电压且无损坏。

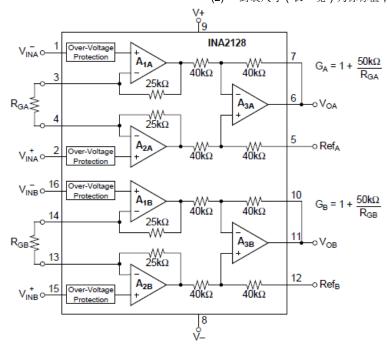
INA2128 经过激光修整,具有极低失调电压 (50 µ V)、 极低温漂 $(0.5 \, \mu \, \text{V/°C})$ 和高共模抑制 $(G \ge 100 \, \text{时为})$ 120dB)。该器件采用低至 ±2.25V 的电源电压,每 IA 静态电流仅 700µA,非常适合电池供电系统和多通道 系统。

INA2128 采用 SOIC-16 封装, 额定温度范围 -40°C 至 +85°C。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸⁽²⁾
INA2128	DW (SOIC , 16)	10.3 mm × 10.3 mm

- (1) 如需了解所有可用封装,请参阅数据表末尾的可订购产品附
- (2)封装尺寸(长×宽)为标称值,并包括引脚(如适用)。



简化原理图



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4 Revision History

注:以前版本的页码可能与当前版本的页码不同

C	hanges from Revision A (April 2007) to Revision B (May 2023)	Page
•	更新了整个文档中的表格、图和交叉参考的编号格式	1
•	添加了封装信息表、引脚配置和功能部分、规格部分、详细描述部分、应用和实施部分、器件和文档	支持
	部分以及 <i>机械、封装和可订购信息</i> 部分	1
•	向 <i>特性</i> 中添加了输入电压噪声、高带宽和温度范围要点	1
•	更改了 <i>特性</i> 要点以显示正确的封装名称	1
•	更改了 <i>应用</i> 要点以显示更新后的链接	1
•	将"封装信息"表的列名称从"封装尺寸(标称值)"更改为"封装尺寸"并添加了有关封装尺寸的注释	圣 1
•	Added single supply specification to Absolute Maximum Ratings	5
•	Added note clarifying output short-circuit to ground in Absolute Maximum Ratings refers to short-circuit	to
	VS / 2	5
•	Added single supply specification to Recommended Operating Conditions	5
•	Changed input common-mode voltage range specification from V - 2 to (V -) + 2 in <i>Recommended</i>	
	Operating Conditions	5
•	Deleted INA128-HT and INA129-HT operating temperature specifications from Recommended Operation	าg
	Conditions	
•	Added specified temperature range to Recommended Operating Conditions	5
•	Added test conditions below Electrical Characterstics title	
•	Changed test condition for offset voltage drift specification in <i>Electrical Characteristics</i> from "TA = TMIN	to
	TMAX" to " TA = -40° to +85°C" for clarity	6
•	Changed "±0.5±0/G" to "±0.5±20/G" in MAX column of Offset voltage RTI vs temperature row of <i>Electric</i>	cal
	Characteristics	6
•	Changed typical long-term stability specification from ±0.1±3/GμV/mo to ±0.2±3/GμV/mo in <i>Electrical</i>	_
	Characteristics	6
•	Deleted typical specification and changed common-mode voltage specification from (V -) + 2 V minimum.	
	(V+) - 2 V maximum across one row in Electrical Characteristics	
•	Deleted typical VCM specifications in <i>Electrical Characteristics</i>	
•	Added test condition of "RS = 0 $^{\Omega}$ " to safe input voltage specification in <i>Electrical Characteristics</i> for class	arity
		6
•	Changed parameter name to Input bias current and added test condition "TA = -40°C to +85°C" to inp	
	current drift specification in <i>Electrical Characteristics</i> for clarity	
•	Changed parameter name to Input offset current drift and added test condition "TA = -40°C to +85°C"	
	input offset current drift specification in Electrical Characteristics for clarity	6

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 ±0.1% in Electrical Characteristics Changed parameter name to Gain drift and added test condition "TA = -40°C to +85°C" for gain described Electrical Characteristics for clarity	0.01% to
 Changed parameter names from "Voltage - Positive" to "Positive output voltage swing" and from "Voltage to "Negative" to "Negative output voltage swing" in <i>Electrical Characteristics</i> Deleted typical positive and negative output voltage swing specifications in <i>Electrical Characteristics</i> Added test condition "Continuous to VS / 2" short-circuit current specification in <i>Electrical Characteristics</i> Changed typical bandwidth specification for G = 10 from 700 kHz to 600 kHz in <i>Electrical Characteristics</i> 	Irift in 6
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• Changed typical bandwidth specification for G = 10 from 700 kHz to 600 kHz in <i>Electrical Characte</i>	
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Changed typical siew rate specification from # y/us to 1.2 y/us in E/ectrical Characteristics	6
• Changed typical settling time specification for G = 1, G = 10, from 7 μs to 9 μs in <i>Electrical Character</i>	teristics
, , , , , , , , , , , , , , , , , , ,	6
Deleted parameter "Temperature Range" as made redundant by "Recommended Operating Conditation "Absolute Maximum Ratings"	<i>tions"</i> and 6
• Changed parameter name to "Total quiescent current" and deleted redundant voltage range, opera temperature range, and specification temperature range specifications from <i>Electrical Characteristi</i>	
Added test conditions below the <i>Typical Characteristics</i> title	
Changed Figure 6-1, Gain vs Frequency	
Changed Figure 6-3, Positive Power Supply Rejection vs Frequency	
Changed Figure 6-4, Negative Power Supply Rejection vs Frequency	
Changed Figure 6-7, Crosstalk vs Frequency	
Changed Figure 6-8, Input-Referred Voltage Noise vs Frequency	
Changed Figure 6-9, Settling Time vs Gain	
Changed Figure 6-11, Input Overvoltage V/I Characteristics	
Changed Figure 6-12, Offset Voltage Warm-Up	8
Changed Output Voltage Swing vs Output Current, into two separate plots, one for positive (Figure one for negative (Figure 6-15)	
Changed Figure 6-22 to Figure 6-24, Large-Signal Step Response	8



5 Pin Configuration and Functions

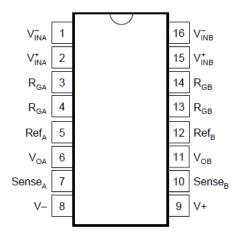


图 5-1. DW Package, 16-Pin SOIC (Top View)

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
.,	Supply voltage	Dual supply, V _S = (V+) - (V -)		±18	V
Vs	Supply voltage	Single supply, $V_S = (V+) - 0 V$		36	V
	Analog input voltage			±40	V
	Output short-circuit ⁽²⁾		Continuous		
T _A	Operating temperature		- 40	125	°C
	Junction temperature			150	°C
	Lead temperature (sold	ering, 10 s)		300	°C
T _{stg}	Storage temperature		- 55	125	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
/ Electrostatic discharge	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	\/
V _(ESD)	Lieurostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±50	v

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	TYP	MAX	UNIT
V	Supply voltage	Single-supply	4.5	30	36	V
V _S Supply voltage	Supply voltage	Dual-supply	±2.25	±15	±18	V
	Input common-mode voltage range for	V _O = 0 V	(V -) + 2		(V+) - 2	V
T _A	Specified temperature		- 40		85	°C

6.4 Thermal Information

		INA	INA12x		
	THERMAL METRIC ⁽¹⁾	D (SOIC)	P (PDIP)	UNIT	
		8 PINS	8 PINS		
R ₀ JA	Junction-to-ambient thermal resistance	110	46.1	°C/W	
R _{θ JC(top)}	Junction-to-case (top) thermal resistance	57	34.1	°C/W	
R ₀ JB	Junction-to-board thermal resistance	54	23.4	°C/W	
ψJT	Junction-to-top characterization parameter	11	11.3	°C/W	
ψ JB	Junction-to-board characterization parameter	53	23.2	°C/W	

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

⁽²⁾ Short-circuit to V_S / 2.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6.5 Electrical Characteristics

at T_A = 25°C, V_S = ±15 V, R_L = 10 k Ω , V_{REF} = 0 V, V_{CM} = V_S / 2, and G = 1 (unless otherwise noted)

	PARAMETER	TES	ST CONDITI	ONS	MIN	TYP	MAX	UNIT
INPUT								
		INA2128U	NA2128U			±10 ±100 / G	±50 ±500 / G	
V _{OS}	Offset voltage (RTI)	INA2128UA		±25 ±100 / G	±125 ±1000 / G	μV		
	05 1 11 115 (DT)		INA2128U			±0.2 ±2 / G	±0.5 ±20 / G	1400
	Offset voltage drift (RTI)	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	INA2128U	A		±0.2 ±5 / G	±1 ±20 / G	μV/°C
DODD	Power-supply rejection		V to +18 V			±0.2 ±20 / G	±1 ±100 / G	1/0/
PSRR	ratio (RTI)	$V_S = \pm 2.25 \text{ V to } \pm 18 \text{ V}$	INA2128U	A		±0.2 ±20 / G	±2 ±200 / G	μV/V
	Long-term stability		•			±0.2 ±3 / G		μV/mo
	Input impedance	Differential				10 2		CO "F
	Input impedance	Common-mode				100 9		GΩ pF
V _{CM}	Common-mode voltage ⁽¹⁾	V _O = 0 V			(V -) + 2		(V+) - 2	V
	Safe input voltage	R _S = 0 Ω					±40	V
			G = 1	INA2128U	80	86		
			0-1	INA2128UA	73	86		
			G = 10	INA2128U	100	106		- dB
CMRR	Common-mode rejection	$\triangle R_S = 1 k\Omega$, $V_{CM} = \pm 13$	G = 10	INA2128UA	93	106		
CIVICK	ratio		G = 100	INA2128U	120	125		
			G = 100	INA2128UA	110	125		
			G = 1000	INA2128U	120	130		
			0 - 1000	INA2128UA	110	130		
INPUT E	BIAS CURRENT							
I _B	Input bias current	INA2128U				±2	±5	nA
'B	input bias ouncil	INA2128UA				±2	±10	117 (
	Input bias current drift	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$				±30		p A /℃
Ios	Input offset current	INA2128U				±1	±5	nA
ios	input onset current	INA2128UA				±1	±10	ПА
	Input offset current drift	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$				±30		pA/℃
NOISE					·			
			f = 10 Hz			10		
e _N	Voltage noise (RTI)	G = 1000, R _S = 0 Ω	f = 100 Hz	f = 100 Hz		8		nV/√ Hz
○N	Voltage Holse (TCTT)	G = 1000, Ng = 0 ss	f = 1 kHz			8		
			f _B = 0.1 Hz	z to 10 Hz		0.2		μV_{PP}
		f = 10 Hz				0.9		pA/√ Hz
	Current noise	f = 1 kHz				0.3		
		f _B = 0.1 Hz to 10 Hz				30		pA_{PP}

6.5 Electrical Characteristics (continued)

at $T_A = 25$ °C, $V_S = \pm 15$ V, $R_L = 10$ k Ω , $V_{REF} = 0$ V, $V_{CM} = V_S / 2$, and G = 1 (unless otherwise noted)

	PARAMETER		V , $V_{CM} = V_S / 2$, and $G = 1$ (un EST CONDITIONS	MIN	TYP	MAX	UNIT	
GAIN								
	Gain equation			1	+ (50 kΩ / R _G)		V/V	
G	Gain			1		10000	V/V	
		0.4	INA2128U		±0.01	±0.024		
		G = 1	INA2128UA		±0.01	±0.1		
		0 10	INA2128U		±0.02	±0.4		
05		G = 10	INA2128UA		±0.02	±0.5	0,	
GE	Gain error	0 100	INA2128U		±0.05	±0.5	- %	
		G = 100	INA2128UA		±0.05	±0.7		
		0 1000	INA2128U		±0.5	±1		
		G = 1000	INA2128UA		±0.5	±2		
	0 : 1:5(2)				±1	±10	10.0	
	Gain drift ⁽²⁾	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	50-k Ω or 49.4-k Ω resistance ⁽³⁾		±25	±100	ppm/°C	
			INA2128U		±0.0001	±0.001		
		$G = 1, V_O = \pm 13.6 V$	INA2128UA		±0.0001	±0.002		
		G = 10	INA2128U		±0.0003	±0.002	% of FSR	
	Gain nonlinearity		INA2128UA		±0.0003	±0.004		
			INA2128U		±0.0005	±0.002		
		G = 100	INA2128UA		±0.0005	±0.004		
		G = 1000 ⁽⁴⁾			±0.001		-	
OUTP	υΤ						I	
	Positive output voltage			(V+) -			V	
	1 ositive output voltage			1.4			v	
	Negative output voltage			(V -) + 1.4			V	
CL	Load capacitance	Stable operation			1000		pF	
I _{SC}	Short-circuit current	Continuous to V _S / 2			+6/ - 15		mA	
FREQ	UENCY RESPONSE							
		G = 1			1.3		MHz	
BW	Bandwidth, - 3 dB	G = 10			600			
DVV	Balluwidili, - 3 ub	G = 100			200		kHz	
		G = 1000			20			
SR	Slew rate	G = 10, V _O = ±10 V			1.2		V/µs	
			G = 1		9			
t_	Settling time	To 0.01%	G = 10		9			
t _S	Jetung une	To 0.01%	G = 100		12		μs	
			G = 1000		80			
	Overload recovery	50% input overload			4		μs	
POWE	R SUPPLY							
IQ	Total quiescent current	V _{IN} = 0 V			±1.4	±1.5	mA	

⁽¹⁾ Input common-mode voltage varies with output voltage; see *Typical Characteristics*.

⁽²⁾ Specified by wafer test.

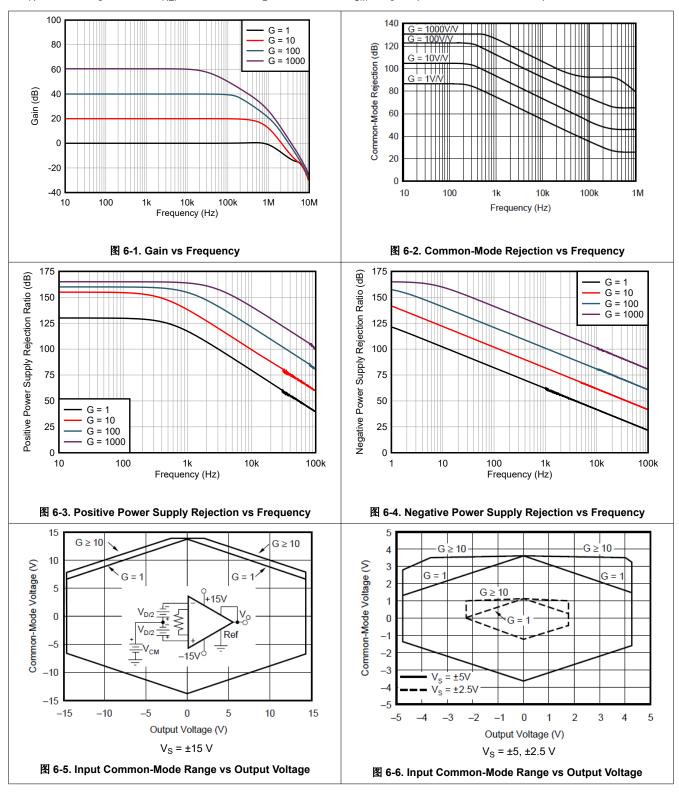
⁽³⁾ Temperature coefficient of the 50-k Ω or 49.4-k Ω term in the gain equation.

⁽⁴⁾ Nonlinearity measurements in G = 1000 are dominated by noise. Typical nonlinearity is ±0.001%.

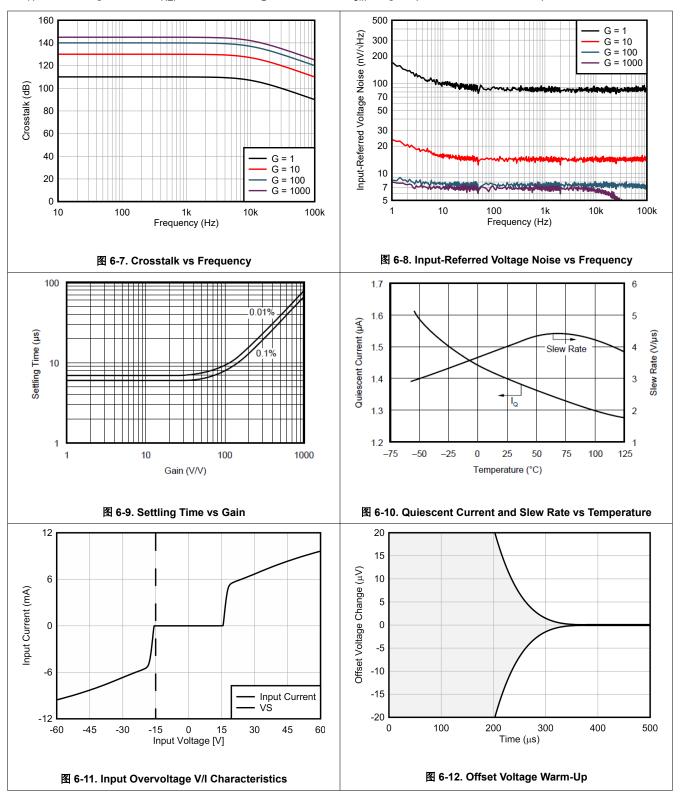


6.6 Typical Characteristics

at T_A = +25°C, V_S = ± 15 V, V_REF = 0 V, G = 1, R_L = 10 k Ω , and V_{CM} = V_S / 2 (unless otherwise noted)

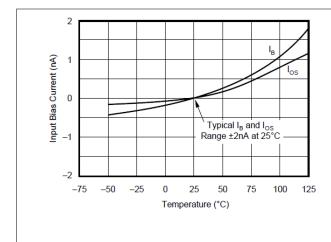


at T_A = +25°C, V_S = ± 15 V, V_REF = 0 V, G = 1, R_L = 10 k Ω , and V_CM = V_S / 2 (unless otherwise noted)





at T_A = +25°C, V_S = ± 15 V, V_REF = 0 V, G = 1, R_L = 10 k Ω , and V_CM = V_S / 2 (unless otherwise noted)



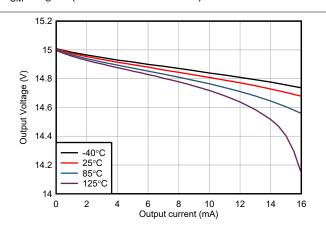
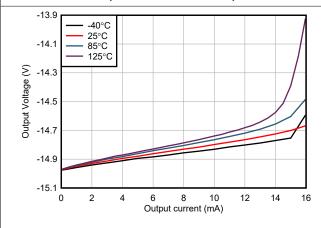


图 6-13. Input Bias Current vs Temperature

图 6-14. Positive Output Voltage Swing vs Output Current



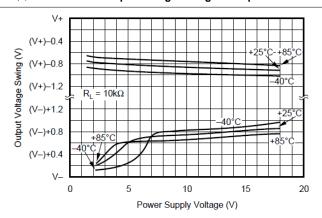
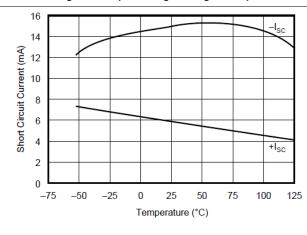


图 6-15. Negative Output Voltage Swing vs Output Current

图 6-16. Output Voltage Swing vs Power Supply Voltage



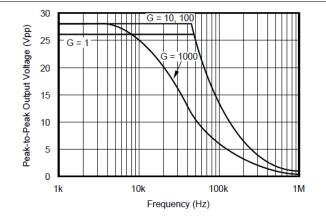
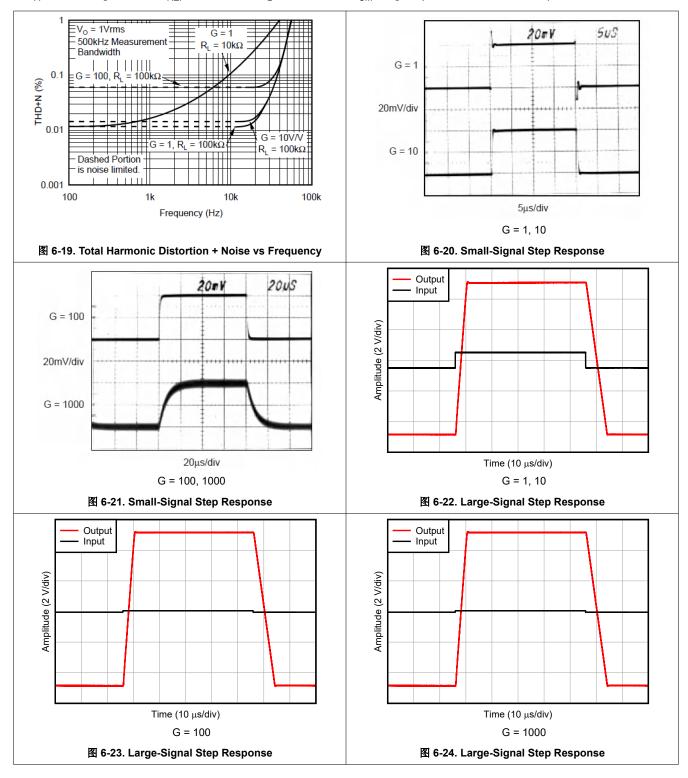


图 6-17. Short-Circuit Output Current vs Temperature

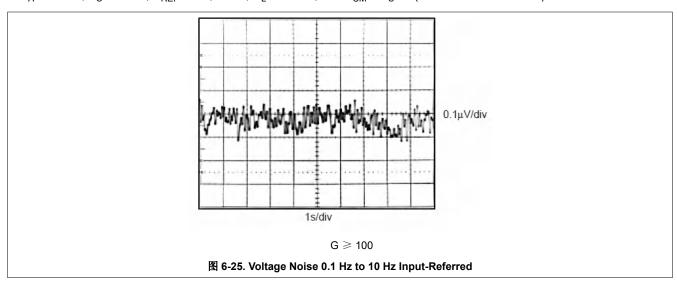
图 6-18. Maximum Output Voltage vs Frequency

at T_A = +25°C, V_S = ±15 V, V_{REF} = 0 V, G = 1, R_L = 10 k Ω , and V_{CM} = V_S / 2 (unless otherwise noted)





at T_A = +25°C, V_S = ± 15 V, V_REF = 0 V, G = 1, R_L = 10 k Ω , and V_CM = V_S / 2 (unless otherwise noted)



7 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Application Information

▼ 7-1 shows the basic connections required for operation of the INA2128. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminals (Ref_A and Ref_B) which are normally grounded. These must be low-impedance connections to assure good common-mode rejection. A resistance of 8 Ω in series with a Ref pin will cause a typical device to degrade to approximately 80 dB CMR (G = 1).

The INA2128 has separate output sense feedback connections, Sense_A and Sense _B. These must be connected to their respective output terminals for proper operation. The output sense connection can be used to sense the output voltage directly at the load for best accuracy.

7.2 Typical Application

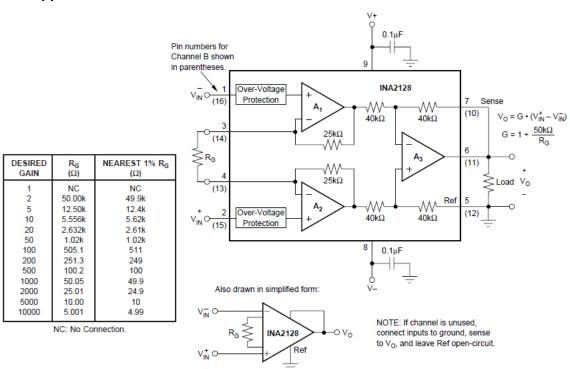


图 7-1. Basic Connections

7.2.1 Setting The Gain

Gain of the INA2128 is set by connecting a single external resistor, RG, connected as shown:

$$G = 1 + \frac{50k\Omega}{R_G}$$
 (1)

Commonly-used gains and resistor values are shown in <a>\mathbb{Z} 7-1.

The 50 k Ω term in 方程式 1 comes from the sum of the two internal feedback resistors, A₁ and A₂. These on-chip metal film resistors are laser-trimmed to accurate absolute values. The accuracy and temperature coefficient of these resistors are included in the gain accuracy and drift specifications of the INA2128.

The stability and temperature drift of the external gain setting resistor, RG, also affects gain. RG's contribution to gain accuracy and drift can be directly inferred from the gain equation (1). Low resistor values required for high gain can make wiring resistance important. Sockets add to the wiring resistance which will contribute additional gain error in gains of approximately 100 or greater.

7.2.2 Dynamic Performance

The typical performance curve <a> 6-1 shows that despite its low quiescent current, the INA2128 achieves wide bandwidth, even at high gain. This is due to its current feedback topology. Settling time also remains excellent at high gain—see <a> 6-9.

7.2.3 Noise Performance

The INA2128 provides very low noise in most applications. Low frequency noise is approximately 0.2 μV_{pp} measured from 0.1 Hz to 10 Hz (G \geqslant 100). This provides dramatically improved noise when compared to state-of-the-art chopper-stabilized amplifiers.

7.2.4 Offset Trimming

The INA2128 is laser-trimmed for low offset voltage and offset voltage drift. Most applications require no external offset adjustment.

7-2 shows an optional circuit for trimming the output offset voltage. The voltage applied to Ref terminal is summed with the output. The op amp buffer provides low impedance at the Ref terminal to preserve good common-mode rejection.

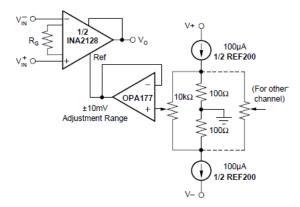


图 7-2. Optional Trimming of Output Offset Voltage

Product Folder Links: INA2128

7.2.5 Input Bias Current Return Path

The input impedance of the INA2128 is extremely high—approximately $10^{10}~\Omega$. However, a path must be provided for the input bias current of both inputs. This input bias current is approximately ± 2 nA. High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current for proper operation.

7-3 shows various provisions for an input bias current path. Without a bias current path, the inputs float to a potential that exceeds the common-mode range of the INA2128 and the input amplifiers saturate.

If the differential source resistance is low, the bias current return path can be connected to one input (see the thermocouple example in $\boxed{8}$ 7-3). With higher source impedance, using two equal resistors provides a balanced input with possible advantages of lower input offset voltage due to bias current and better high-frequency common-mode rejection.

7.2.6 Input Common-Mode Range

The linear input voltage range of the input circuitry of the INA2128 is from approximately 1.4 V less than the positive supply voltage to 1.7 V greater than the negative supply. As a differential input voltage causes the output voltage increase, the linear input range is limited by the output voltage swing of amplifiers A_1 and A_2 . Therefore, the linear common-mode input range is related to the output voltage of the complete amplifier. This behavior also depends on supply voltage—see performance curves $\boxed{8}$ 6-6 and $\boxed{8}$ 6-5.

Input-overload can produce an output voltage that appears normal. For example, if an input overload condition drives both input amplifiers to the positive output swing limit, the difference voltage measured by the output amplifier is near zero. The output of the INA2128 is near 0 V even though both inputs are overloaded.

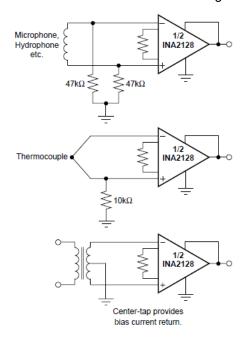


图 7-3. Providing an Input Common-Mode Current Path

7.2.7 Low-Voltage Operation

The INA2128 can be operated on power supplies as low as ± 2.25 V. Performance remains excellent with power supplies ranging from ± 2.25 V to ± 18 V. Most parameters vary only slightly throughout this supply voltage range —see \dagger 6.6. Operation at very low supply voltage requires careful attention to make sure that the input voltages remain within the linear range. Voltage swing requirements of internal nodes limit the input common-mode range with low power-supply voltage. Typical performance curves, \boxtimes 6-5 and \boxtimes 6-6, show the range of linear operation for ± 15 -V, ± 5 -V, and ± 2.5 -V supplies.

7.2.8 Input Protection

The inputs of the INA2128 are individually protected for voltages up to ±40 V. For example, a condition of $^-$ 40 V on one input and +40 V on the other input will not cause damage. Internal circuitry on each input provides low series impedance under normal signal conditions. To provide equivalent protection, series input resistors would contribute excessive noise. If the input is overloaded, the protection circuitry limits the input current to a safe value of approximately 1.5 mA to 5 mA. The typical performance curve "Input Bias Current vs Common-Mode Input Voltage" shows this input current limit behavior. The inputs are protected even if the power supplies are disconnected or turned off.

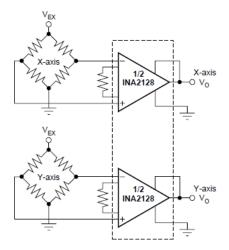


图 7-4. Two-Axis Bridge Amplifier

7.2.9 Channel Crosstalk

The two channels of the INA2128 are completely independent, including all bias circuitry. At dc and low frequency, there is virtually no signal coupling between channels. Crosstalk increases with frequency and depends on circuit gain, source impedance, and signal characteristics.

As source impedance increases, careful circuit layout helps achieve lowest channel crosstalk. Most crossstalk is produced by capacitive coupling of signals from one channel to the input section of the other channel. To minimize coupling, separate the input traces as far as practical from any signals associated with the opposite channel. A grounded guard trace surrounding the inputs helps reduce stray coupling between channels. Run the differential inputs of each channel parallel to each other or directly adjacent on top and bottom side of a circuit board. Stray coupling then tends to produce a common-mode signal which is rejected by the IA input.

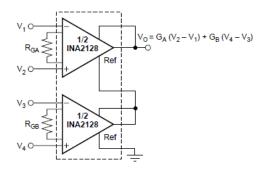


图 7-5. Sum of Differences Amplifier

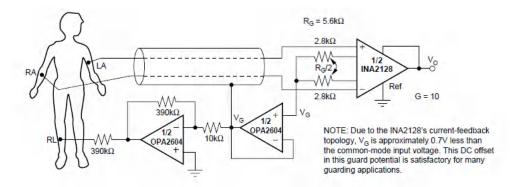


图 7-6. ECG Amplifier With Right-Leg Drive



8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 接收文档更新通知

要接收文档更新通知,请导航至 ti.com 上的器件产品文件夹。点击*订阅更新* 进行注册,即可每周接收产品信息更改摘要。有关更改的详细信息,请查看任何已修订文档中包含的修订历史记录。

8.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料,可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者"按原样"提供。这些内容并不构成 TI 技术规范,并且不一定反映 TI 的观点;请参阅 TI 的《使用条款》。

8.3 Trademarks

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ESD 的损坏小至导致微小的性能降级,大至整个器件故障。精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.5 术语表

TI术语表本术语表列出并解释了术语、首字母缩略词和定义。

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
INA2128U	Active	Production	SOIC (DW) 16	40 TUBE	Yes	(4) NIPDAU	(5) Level-2-260C-1 YEAR	-40 to 85	INA2128U
INA2128U.B	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	INA2128U
INA2128U/1K	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-	INA2128U
INA2128U/1K.B	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	INA2128U
INA2128U1G4	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	INA2128U
INA2128U1G4.B	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	INA2128U
INA2128UA	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-	(INA2128U, INA2128 UA) A
INA2128UA.B	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	(INA2128U, INA2128 UA) A
INA2128UA/1K	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-	(INA2128U, INA2128 UA) A
INA2128UA/1K.B	Active	Production	SOIC (DW) 16	1000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	(INA2128U, INA2128 UA) A
INA2128UAG4	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	INA2128UA
INA2128UAG4.B	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	INA2128UA

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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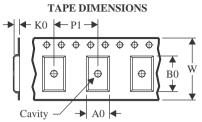
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

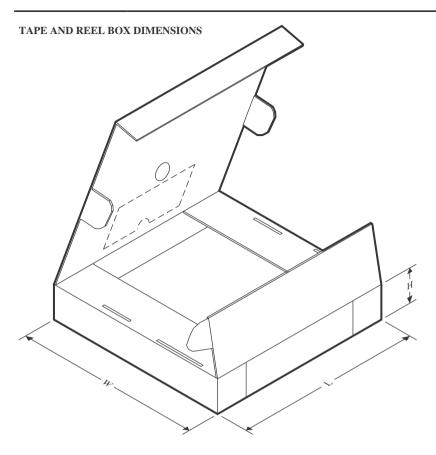


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA2128U/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
INA2128UA/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
INA2128U/1K	SOIC	DW	16	1000	350.0	350.0	43.0	
INA2128UA/1K	SOIC	DW	16	1000	350.0	350.0	43.0	

PACKAGE MATERIALS INFORMATION

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TUBE



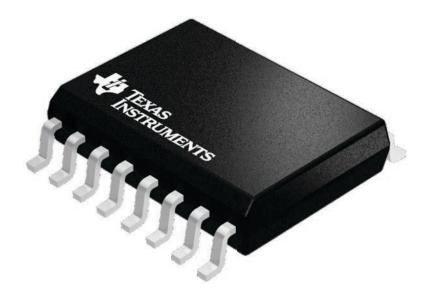
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
INA2128U	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128U.B	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128U1G4	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128U1G4.B	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128UA	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128UA.B	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128UAG4	DW	SOIC	16	40	506.98	12.7	4826	6.6
INA2128UAG4.B	DW	SOIC	16	40	506.98	12.7	4826	6.6

7.5 x 10.3, 1.27 mm pitch

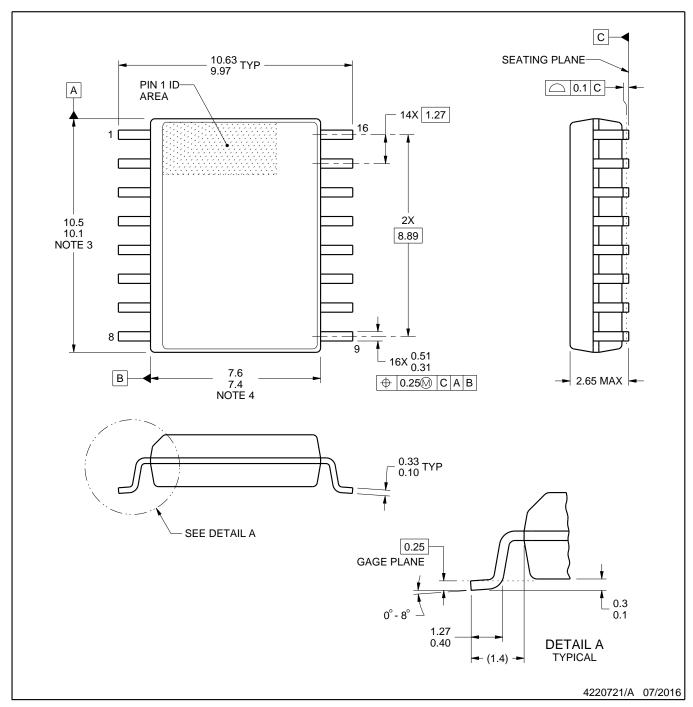
SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





SOIC



NOTES:

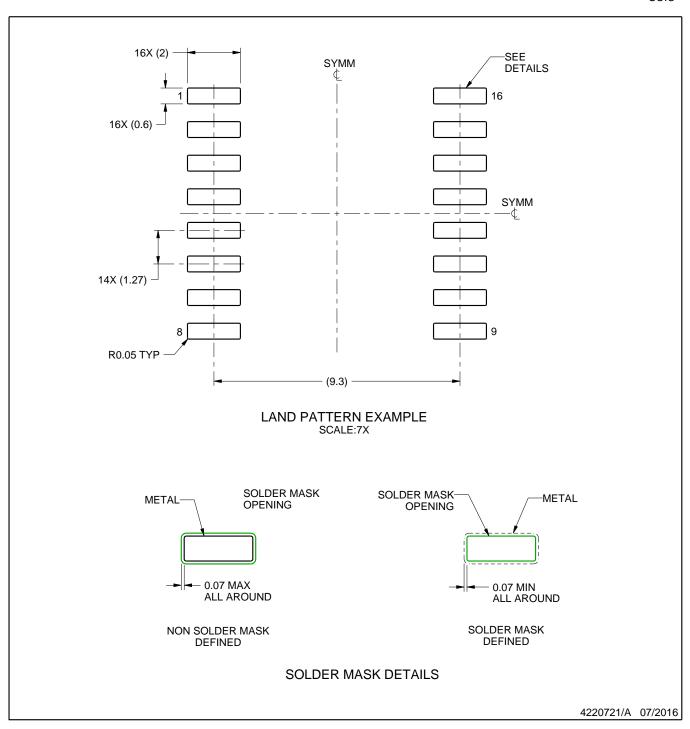
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
- 5. Reference JEDEC registration MS-013.



SOIC



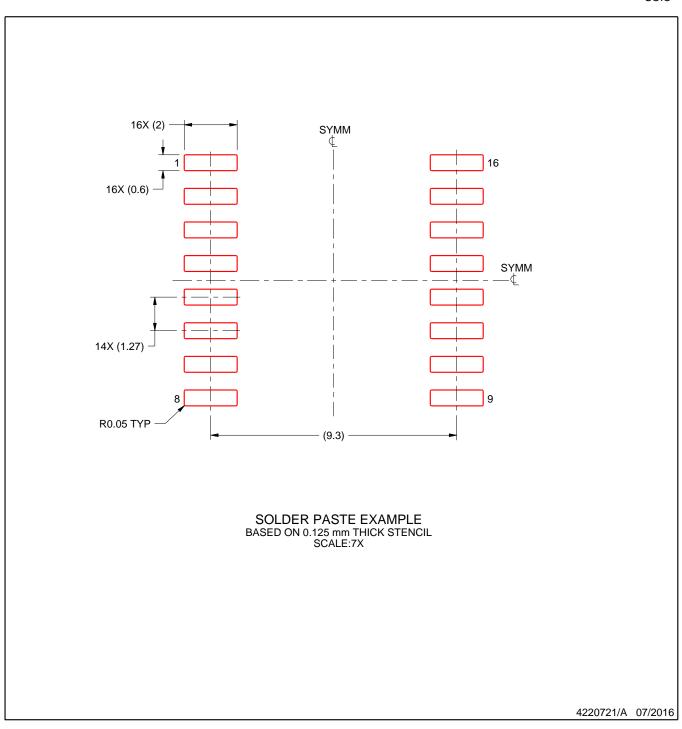
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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